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ABSTRACT OF THE DISCLOSURE

A slit is formed in a polyimide substrate and a copper wiring pattern is formed on the surface of the polyimide substrate. Moreover, solder resist, which has a young's modulus in the range of 5 kgf/mm² to 70 kgf/mm² and contains a filler in the range of 10 wt% to 40 wt%, is formed on the copper wiring pattern. Thus, the copper wiring pattern becomes less susceptible to disconnection, and it is possible to provide a flex TCP semiconductor device with high manufacturing yield.

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